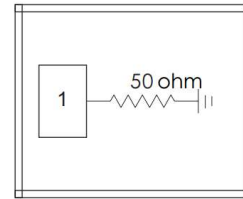


Performance

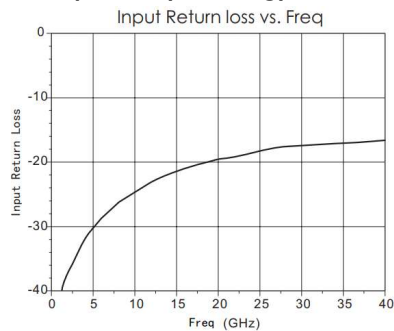
- Frequency: DC-40GHz
- Input Return Loss: 18dB
- Power Handling: 1W/CW
- Chip size: 0.5*0.4*0.1mm

Function Diagram



Parameter	Min	Typical	Max	Unit
Frequency Range	DC-40			GHz
Input Return Loss	-	18	-	dB
Power Handling	-	-	1	W

Test Curves (Die chip testing)



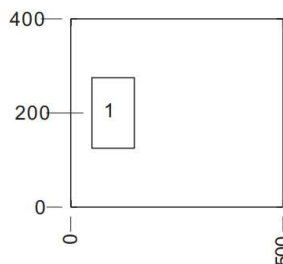
Absolute Max Ratings

RF Input Power	+30dBm
Junction Temperature	175°C
Storage Temperature	-65~+150°C
Operating Temperature	-55~+125°C
Static Protection Grade	Class 1A



ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS

Outline Size

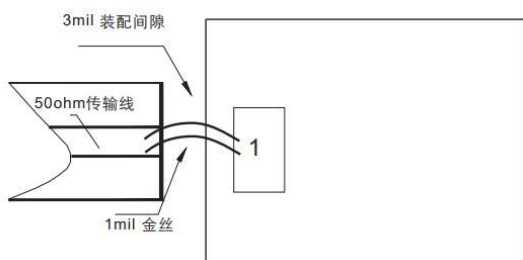


Note:

Unit: um

1. Bottom side is gold plated
2. Bottom side is GND
3. Bonding pads is gold plated
Pad size: 150*100 um
4. Don't bonding on thru holes
5. Tolerance: ±50um

Assembly Drawing



Typical assemble gap: 0.076~0.152mm (3~6mils)

Bonding Pads Definition

Number	Symbol	Description
1	RFin	RF input port 50 ohm impedance
	GND	Bottom side of chip must be grounded